

Supplementary Materials for Silicon Surface Patterning via Galvanic Microcontact Imprinting Lithography

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Supplementary Figures



Fig. S1. The photogram image of the custom-built hydrostatic pressure device.

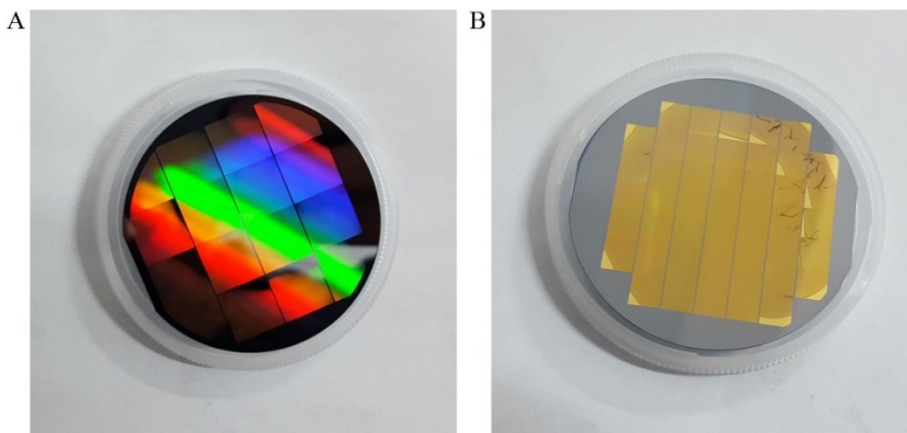


Fig. S2. The photogram images of gold pillar (A) and grating (B) moulds prepared on silicon wafers.

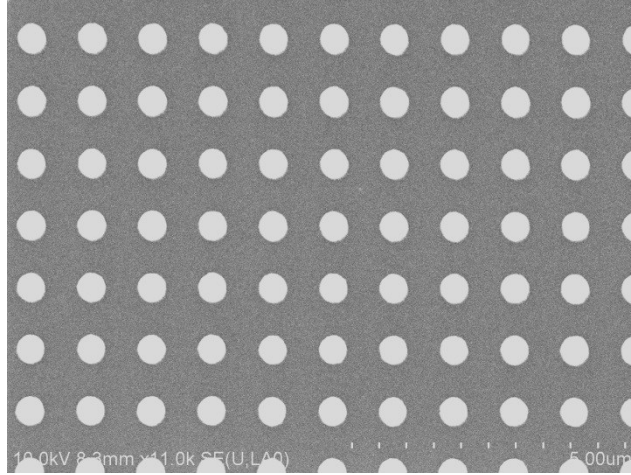


Fig. S3. SEM image of the gold pillar mould after more than 10 times GML use, showing no observable damage.

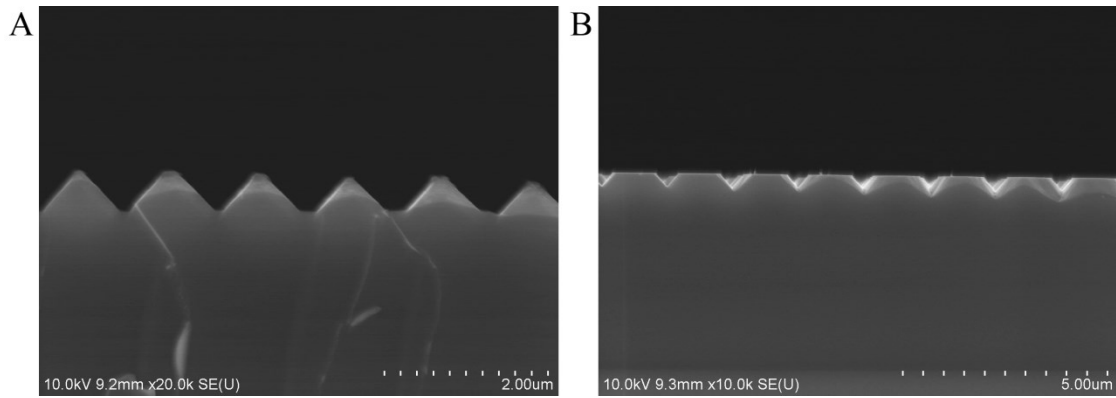


Fig. S4. The cross-sectional SEM images of upright (A) and inverted (B) silicon pyramids prepared by GML process and wet etching in KOH solution.